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### Understanding [Embedded - Microprocessors](#)

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

### Applications of [Embedded - Microprocessors](#)

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

#### Details

Product Status	Obsolete
Core Processor	EC000
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	10MHz
Co-Processors/DSP	-
RAM Controllers	-
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	0°C ~ 70°C (TA)
Security Features	-
Package / Case	64-QFP
Supplier Device Package	64-QFP (14x14)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/nxp-semiconductors/mc68ec000aa10">https://www.e-xfl.com/product-detail/nxp-semiconductors/mc68ec000aa10</a>

The primary features of the MC68SEC000 embedded processor include the following:

- Direct Replacement for the MC68EC000
  - Pin-for-pin compatibility with the MC68EC000 in the plastic QFP and TQFP packages
  - Vast selection of existing third-party development tools for the MC68EC000 support the MC68SEC000
  - Software written for the MC68EC000 will run unchanged on the MC68SEC000
- Power Management
  - Low-power HCMOS technology
  - Static design allows for stopping the processor clock
  - 3.3V or 5V operation
  - Typical 0.5μA current consumption at 3.3V in sleep mode
- Software Strength
  - Fully upward object-code compatible with other M68000 Family products
  - M68000 architecture allows effective assembly code with a C compiler
- Upgrade
  - Fully upward code-compatible with higher performance 680x0 and 68300 Family members
  - ColdFire® code-compatible with minor modifications

## 1. MC68HC000

The primary benefit of the MC68HC000 is reduced power consumption. The device dissipates less power (by an order of magnitude) than the NMOS MC68000.

The MC68HC000 is an implementation of the M68000 16-/32 bit microprocessor architecture. The MC68HC000 has a 16-bit data bus implementation of the MC68000 and is upward code-compatible with the MC68010 and the MC68020 32-bit implementation of the architecture.

### 1.1 MC68HC001

The MC68HC001 provides a functional extension to the MC68HC000 HCMOS 16-/32-bit microprocessor with the addition of statically selectable 8- or 16-bit data bus operation. The MC68HC001 is object-code compatible with the MC68HC000. You can migrate code written for the MC68HC001 without modification to any member of the M68000 Family.

### 1.2 MC68EC000

The MC68EC000 is an economical high-performance embedded controller designed to suit the needs of the cost-sensitive embedded-controller market. The HCMOS MC68EC000 has an internal 32-bit architecture that is supported by a statically selectable 8- or 16-bit data bus. This architecture provides a fast and efficient processing device that can satisfy the requirements of sophisticated applications based on high-level languages.

The MC68EC000 is fully object-code compatible with the MC68000. You can migrate code written for the MC68EC000 without modification to any member of the M68000 Family.

The MC68EC000 brings the performance level of the M68000 Family to cost levels previously associated with 8-bit microprocessors. The MC68EC000 benefits from the rich M68000 instruction set and its related high code density with low memory bandwidth requirements.

### 1.3 MC68SEC000

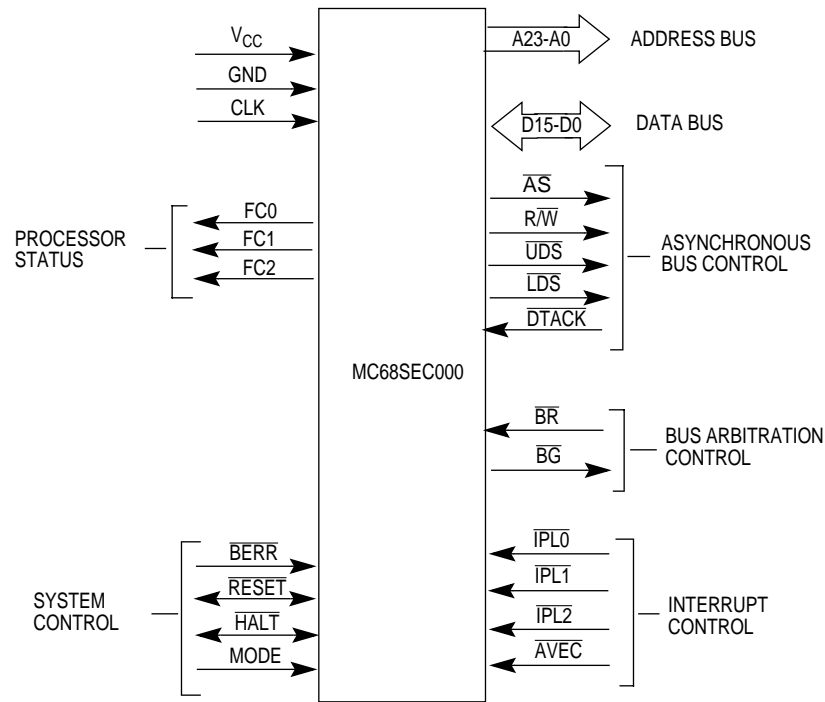
The MC68SEC000 is a cost-effective static embedded processor engineered for low-power applications. In addition to providing the substantial cost and performance benefits of the MC68EC000, the low-power mode of the MC68SEC000 provides significant advantages in power consumption and power management. The typical current consumption of the MC68SEC000 is only 0.5 $\mu$ A in static standby mode and 15.0mA in normal 3.3V operation. The MC68SEC000 operates in either 3.3V or 5.0V systems. The remarkably low power consumption, small footprint packages, and static implementation are combined in the MC68SEC000 for low-power applications such as portable measuring equipment, electronic games, and battery-operated hand-held consumer products.

The HCMOS MC68SEC000's static architecture is a direct replacement for the MC68EC000, which offers the lowest cost entry point to 32-bit processing. The internal 32-bit architecture provides fast and efficient processing that satisfies the requirements of sophisticated applications based on high-level languages.

All of the existing third-party developer tools widely available for the MC68EC000 will directly support the MC68SEC000. You can find detailed descriptions of these tools in the *High Performance Embedded Systems Source Catalog*.

## 2.0 SIGNAL DESCRIPTION

Change Figure 3-3 on Page 3-2.



**Figure 1. Input and Output Signals (MC68EC000 and MC68SEC000)**

### 2.1 Data Bus (D15-D0)

In Section 3.2 on page 3-4, replace “The MC68EC000 and MC68HC001 use D7-D0 in 8-bit mode, and D15-D8 are undefined.” with “Using the MC68HC001, MC68EC000, and MC68SEC000 mode pin, you can statically select either 8- or 16-bit modes for data transfer. The MC68EC000, MC68SEC000, and MC68HC001 use D7-D0 in 8-bit mode. D15-D8 are undefined.”

### 2.2 Bus Arbitration Control

In Section 3.4 on page 3-5, the sentence “In the 48-pin version of the MC68008 and MC68EC000, no pin is available for the bus grant acknowledge signal; this microprocessor uses a two-wire bus arbitration scheme.” should read “In the 64-pin MC68EC000 and MC68SEC000, no pin is available for the bus grant acknowledge signal. These microprocessors use a two-wire bus arbitration scheme.”

### 2.3 System Control

The Mode subsection heading of Section 3.6 on page 3-7 should read “Mode (MODE) (MC68HC001/68EC000/68SEC000).”

### 2.4 MC68SEC000 Low-Power Mode

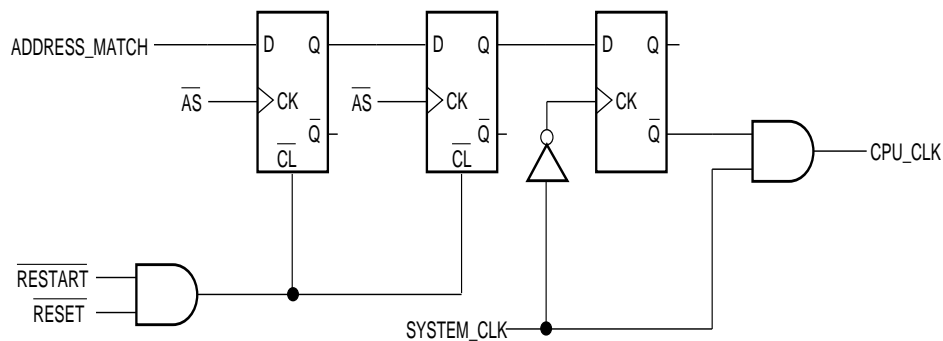
Add the following to Sections 4 and 5, Bus Operation.

The MC68SEC000 has been redesigned to provide fully static- and low-power operation. This section describes the recommended method for placing the MC68SEC000 into a low-power mode to reduce the

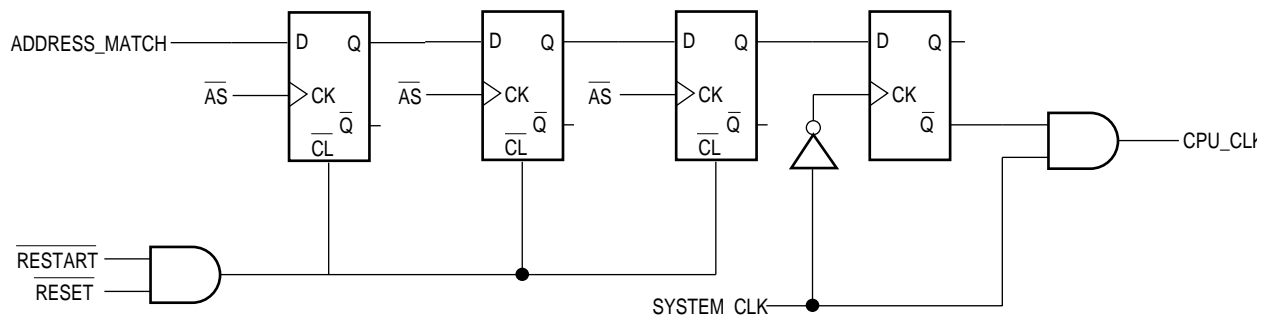
power consumption to its quiescent value<sup>1</sup> while maintaining the internal state of the processor. The low-power mode described below will be routinely tested as part of the MC68SEC000 test vectors provided by Motorola.

To successfully enter the low-power mode, the MC68SEC000 must first be in the supervisor mode. A recommended method for entering the low-power mode is to use the TRAP instruction, which causes the processor to begin exception processing, thus entering the supervisor mode. External circuitry should accomplish the following steps during the trap routine:

1. Externally detect a write to the low-power address. You select this address which can be any address in the 16 Mbyte addressing range of the MC68SEC000. A write to the low-power address can be detected by polling A23–A0, R/W, and FC2–FC0. When the low-power address is detected, R/W is a logic low, and the function codes have a five (101) on their output, the processor is writing to the low-power address in supervisor mode and user-designed circuitry should assert the ADDRESS\_MATCH signal shown in Figure 2 and Figure 3.



**Figure 2. MC68SEC000 Low-Power Circuitry for 16-Bit Data Bus**



**Figure 3. MC68SEC000 Low-Power Circuitry for 8-Bit Data Bus**

2. Execute the STOP instruction. The external circuitry shown in Figure 2 and Figure 3 will count the number of bus cycles starting with the write to the low-power address and will stop the processor clock on the first falling edge of the system clock after the bus cycle that reads the immediate data of the STOP instruction. Figure 3 has one more flip-flop than Figure 2 because the MC68SEC000 in

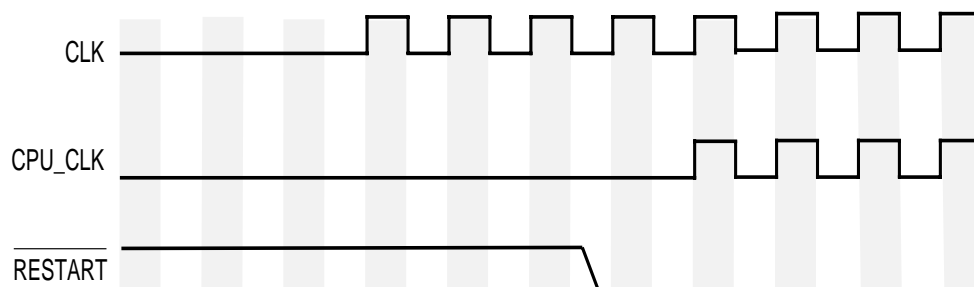
<sup>1</sup>. The preliminary specification for the MC68SEC000's current drain while in the low-power mode is  $I_{dd} < 2\mu A$  for 3.3V operation and  $I_{dd} < 5\mu A$  for 5.0V operation.

After the previous steps are completed, the MC68SEC000 will remain in the low-power mode until it recognizes the appropriate interrupt. External logic will also have to poll IPLB2–IPLB0 to detect the proper interrupt. When the correct interrupt level is received, the following steps will bring the processor out of the low-power mode:

1. Restart the system clock if it was stopped.
2. Wait for the system clock to become stable.
3. Assert the  $\overline{\text{RESTART}}$  signal. This will cause the processor's clock to start on the next falling edge of the system clock. Figure 6 shows the timing for bringing the processor out of the low-power mode. Both the  $\overline{\text{RESTART}}$  and  $\overline{\text{RESET}}$  signals are subject to the asynchronous setup time as specified in the Electrical Characteristics section of this addendum.

## WARNING

The system clock must be stable before the  $\overline{\text{RESTART}}$  signal is asserted to prevent glitches in the clock. An unstable clock can cause unpredictable results in the MC68SEC000.

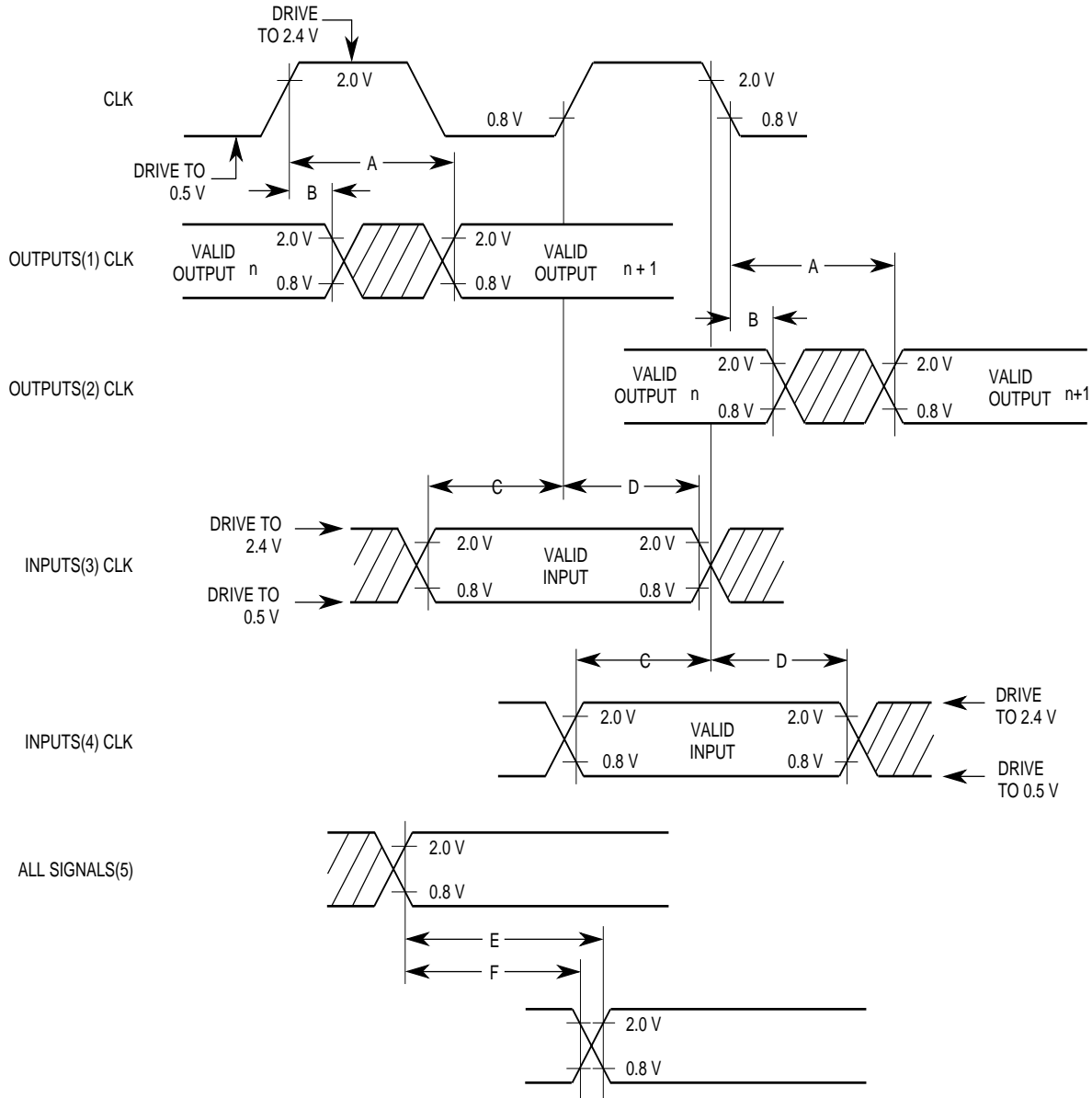


**Figure 6. MC68SEC000 Clock Start Timing**

4. If the MC68SEC000 was placed in a three-state condition, the  $\overline{\text{BR}}$  signal must be negated before the processor can begin executing instructions.

## 4.0 MC68SEC000 AC ELECTRICAL SPECIFICATIONS

Replace Figure 10-2 on page 10-6 with Figure 7.



### NOTES:

1. This output timing is applicable to all parameters specified relative to the rising edge of the clock.
2. This output timing is applicable to all parameters specified relative to the falling edge of the clock.
3. This input timing is applicable to all parameters specified relative to the rising edge of the clock.
4. This input timing is applicable to all parameters specified relative to the falling edge of the clock.
5. This timing is applicable to all parameters specified relative to the assertion/negation of another signal.

### LEGEND:

- A. Maximum output delay specification.
- B. Minimum output hold time.
- C. Minimum input setup time specification.
- D. Minimum input hold time specification.
- E. Signal valid to signal invalid specification (maximum or minimum).
- F. Signal valid to signal invalid specification (maximum or minimum).

**Figure 7. Drive Levels and Test Points for AC Specifications - applies to all parts**

## 5.0 MC68SEC000 DC ELECTRICAL SPECIFICATIONS

Add the following table to Section 10.13 on page 10-23.

( $V_{CC} = 5.0 \text{ Vdc} \pm 5\%$ ,  $3.3 \text{ Vdc} \pm 10\%$ ;  $GND = 0 \text{ Vdc}$ ;  $T_A = T_L \text{ to } T_H$ )

CHARACTERISTIC	SYMBOL	3.3 V		5.0 V		UNIT
		MIN	MAX	MIN	MAX	
Input High Voltage	$V_{IH}$	2.0	$V_{CC}$	2.0	$V_{CC}$	V
Input Low Voltage	$V_{IL}$	GND	0.8	GND – 0.5	0.8	V
Input Leakage Current $\overline{BERR}$ , $\overline{BR}$ , $\overline{DTACK}$ , CLK, $\overline{IPL2}$ – $\overline{IPL0}$ , $\overline{AVEC}$ MODE, HALT, RESET	$I_{in}$	—	2.5 20	—	2.5 20	uA
Three-State (Off State) Input Current	$I_{TSI}$	—	2.5	—	2.5	uA
Output High Voltage	$V_{OH}$	2.4	—	$V_{CC}-0.75$	—	V
Output Low Voltage (IOL = 1.6 mA) $\overline{HALT}$ (IOL = 3.2 mA) A23–A0, $\overline{BG}$ , FC2–FC0 (IOL = 5.0 mA) $\overline{RESET}$ (IOL = 5.3 mA) $\overline{AS}$ , D15–D0, $\overline{LDS}$ , R/W, $\overline{UDS}$	$V_{OL}$	— — — —	0.5 0.5 0.5 0.5	— — — —	0.5 0.5 0.5 0.5	V
Current Dissipation* f = 0 Hz	$I_D$	—	0.7	—	1.0	mA
f=10MHz		—	10	—	15	mA
f=16 MHz		—	15	—	25	mA
f= 20 MHz		—	20	—	30	mA
Capacitance ( $V_{in} = 0 \text{ V}$ , $T_A = 25^\circ\text{C}$ , Frequency = 1 MHz)**	$C_{in}$	—	20.0	—	20.0	pF
Load Capacitance $\overline{HALT}$ All Others	CL	—	70 130	—	70 130	pF

\*During normal operation, instantaneous  $V_{CC}$  current requirements may be as high as 1.5A.

Currents listed are with no loading.

\*\*Capacitance is periodically sampled rather than 100% tested.



## 7.0 MC68SEC000 AC ELECTRICAL SPECIFICATIONS — READ AND WRITE CYCLES

Add the following table and Figures 9 and 10 to Section 10.16.

Applies to 3.3V and 5V.

(GND = 0 V;  $T_A = T_L$  to  $T_H$ ; see Figures 3 and 4)

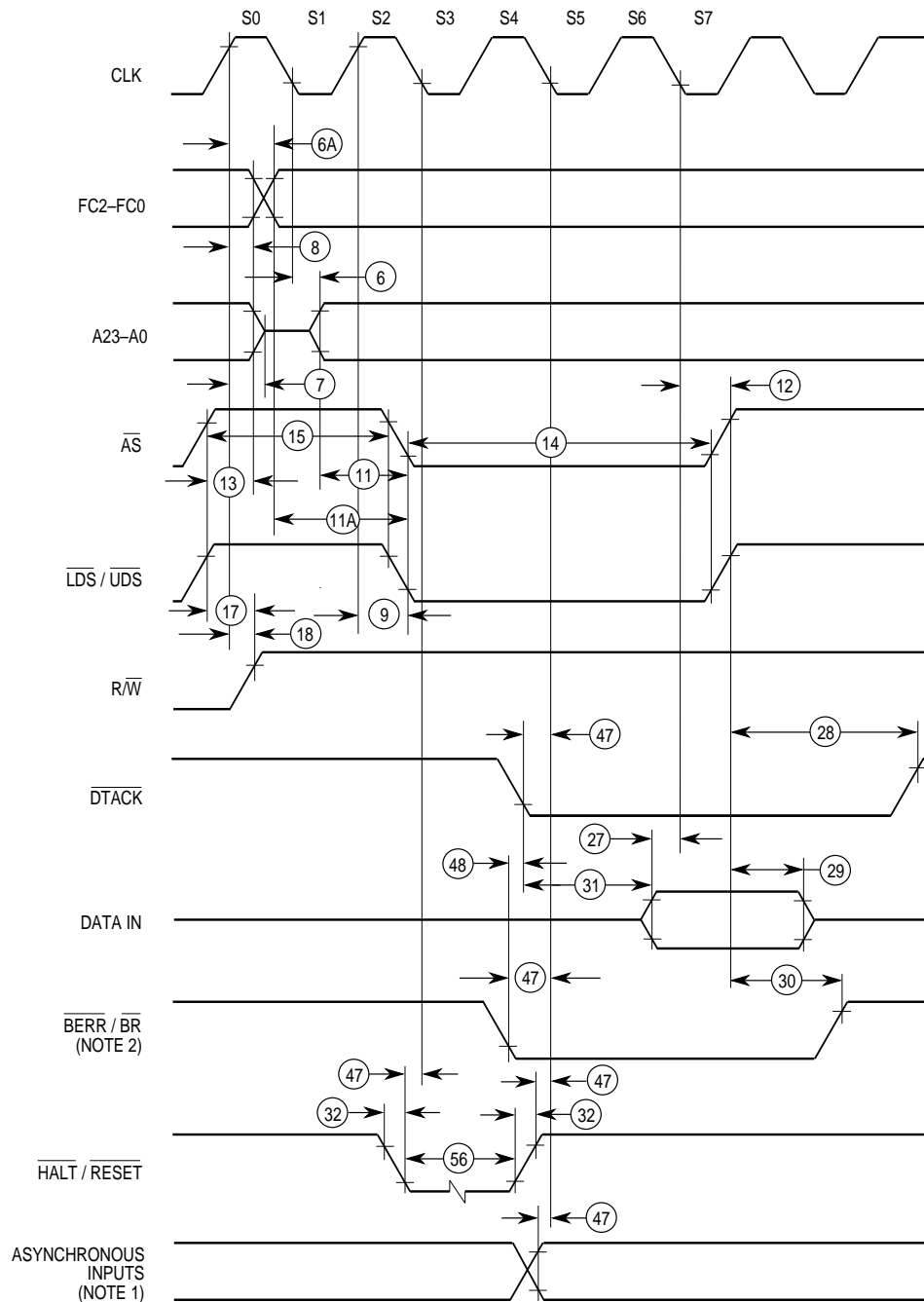
NUM	CHARACTERISTIC	10MHz		16MHz		20MHz		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
6	Clock Low to Address Valid	—	35	—	30	—	25	ns
6A	Clock High to FC Valid	0	35	0	30	0	25	ns
7	Clock High to Address, Data Bus High Impedance (Maximum) (Write)	—	55	—	50	—	42	ns
8	Clock High to Address, FC Invalid (Minimum)	0	—	0	—	0	—	ns
9 <sup>1</sup>	Clock High to $\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Asserted	3	35	3	30	3	25	ns
11 <sup>2</sup>	Address Valid to $\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Asserted (Read)/ $\overline{AS}$ Asserted (Write)	20	—	15	—	10	—	ns
11A <sup>2</sup>	FC Valid to $\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Asserted (Read)/ $\overline{AS}$ Asserted (Write)	45	—	45	—	40	—	ns
12 <sup>1</sup>	Clock Low to $\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Negated	3	35	3	30	3	25	ns
13 <sup>2</sup>	$\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Negated to Address, FC Invalid	15	—	15	—	10	—	ns
14 <sup>2</sup>	$\overline{AS}$ (and $\overline{LDS}$ , $\overline{UDS}$ Read) Width Asserted	195	—	120	—	100	—	ns
14A <sup>2</sup>	$\overline{LDS}$ , $\overline{UDS}$ Width Asserted (Write)	95	—	60	—	50	—	ns
15 <sup>2</sup>	$\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Width Negated	105	—	60	—	50	—	ns
16	Clock High to Control Bus High Impedance	—	55	—	50	—	42	ns
17 <sup>2</sup>	$\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Negated to $R/\overline{W}$ Invalid	15	—	15	—	10	—	ns
18 <sup>1</sup>	Clock High to $R/\overline{W}$ High (Read)	0	35	0	30	0	25	ns
20 <sup>1</sup>	Clock High to $R/\overline{W}$ Low (Write)	0	35	0	30	0	25	ns
20A <sup>2,6</sup>	$\overline{AS}$ Asserted to $R/\overline{W}$ Low (Write)	—	10	—	10	—	10	ns
21 <sup>2</sup>	Address Valid to $R/\overline{W}$ Low (Write)	0	—	0	—	0	—	ns
21A <sup>2</sup>	FC Valid to $R/\overline{W}$ Low (Write)	50	—	30	—	25	—	ns
22 <sup>2</sup>	$R/\overline{W}$ Low to $\overline{DS}$ Asserted (Write)	50	—	30	—	25	—	ns
23	Clock Low to Data-Out Valid (Write)	—	35	—	30	—	25	ns
25 <sup>2</sup>	$\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Negated to Data-Out Invalid (Write)	30	—	15	—	10	—	ns
26 <sup>2</sup>	Data-Out Valid to $\overline{LDS}$ , $\overline{UDS}$ Asserted (Write)	30	—	15	—	10	—	ns
27 <sup>5</sup>	Data-In Valid to Clock Low (Setup Time on Read)	5	—	5	—	5	—	ns
28 <sup>2</sup>	$\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Negated to $\overline{DTACK}$ Negated (Asynchronous Hold)	0	110	0	110	0	95	ns
28A	Clock High to $\overline{DTACK}$ Negated	0	110	0	110	0	95	ns

## AC ELECTRICAL SPECIFICATIONS — READ AND WRITE CYCLES (Continued)

NUM	CHARACTERISTIC	10MHz		16MHz		20MHz		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
29	$\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Negated to Data-In Invalid (Hold Time on Read)	0	—	0	—	0	—	ns
29A	$\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Negated to Data-In High Impedance (Read)	—	150	—	90	—	75	ns
30	$\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Negated to $\overline{BERR}$ Negated	0	—	0	—	0	—	ns
31 <sup>2,5</sup>	$\overline{DTACK}$ Asserted to Data-In Valid (Setup Time on Read)	—	65	—	50	—	42	ns
32	$\overline{HALT}$ and $\overline{RESET}$ Input Transition Time	0	150	0	150	0	150	ns
33	Clock High to $\overline{BG}$ Asserted	—	35	—	30	—	25	ns
34	Clock High to $\overline{BG}$ Negated	—	35	—	30	—	25	ns
35	$\overline{BR}$ Asserted to $\overline{BG}$ Asserted	1.5	3.5	1.5	3.5	1.5	3.5	Clks
36 <sup>7</sup>	$\overline{BR}$ Negated to $\overline{BG}$ Negated	1.5	3.5	1.5	3.5	1.5	3.5	Clks
38	$\overline{BG}$ Asserted to Control, Address, Data Bus High Impedance ( $\overline{AS}$ Negated)	—	55	—	50	—	42	ns
39	$\overline{BG}$ Width Negated	1.5	—	1.5	—	1.5	—	Clks
44	$\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ Negated to $\overline{AVEC}$ Negated	0	55	0	50	0	42	ns
47 <sup>5</sup>	Asynchronous Input Setup Time	5	—	5	—	5	—	ns
48 <sup>2,3</sup>	$\overline{BERR}$ Asserted to $\overline{DTACK}$ Asserted	20	—	10	—	10	—	ns
52	Data-In Hold from Clock High	0	—	0	—	0	—	ns
53	Data-Out Hold from Clock High (Write)	0	—	0	—	0	—	ns
55	$R/\overline{W}$ Asserted to Data Bus Impedance Change (Write)	20	—	10	—	0	—	ns
56 <sup>4</sup>	$\overline{HALT}$ , $\overline{RESET}$ Pulse Width	10	—	10	—	10	—	Clks
58 <sup>7</sup>	$\overline{BR}$ Negated to $\overline{AS}$ , $\overline{LDS}$ , $\overline{UDS}$ , $R/\overline{W}$ Driven	1.5	—	1.5	—	1.5	—	Clks
58A <sup>7</sup>	$\overline{BR}$ Negated to $\overline{FC}$ Driven	1	—	1	—	1	—	Clks

## Applies to 3.3V and 5V.

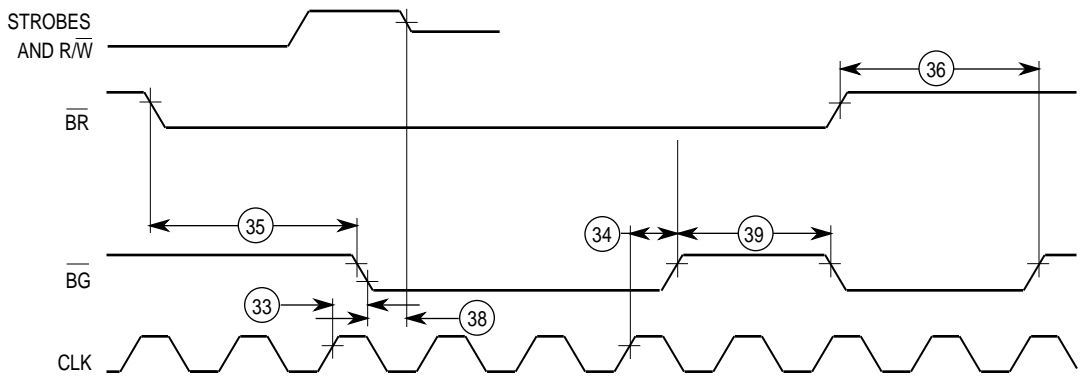
- NOTES: 1. For a loading capacitance of less than or equal to 50 pF, subtract 5 ns from the value given in the maximum columns.
2. Actual value depends on clock period.
3. If #47 is satisfied for both  $\overline{DTACK}$  and  $\overline{BERR}$ , #48 may be ignored. In the absence of  $\overline{DTACK}$ ,  $\overline{BERR}$  is an asynchronous input using the asynchronous input setup time (#47).
4. For power-up, the MC68SEC000 must be held in the reset state for 100 ms to allow stabilization of on-chip circuitry. After the system is powered up, #56 refers to the minimum pulse width required to reset the controller.
5. If the asynchronous input setup time (#47) requirement is satisfied for  $\overline{DTACK}$ , the  $\overline{DTACK}$  asserted to data setup time (#31) requirement can be ignored. The data must only satisfy the data-in to clock low setup time (#27) for the following clock cycle.
6. When  $\overline{AS}$  and  $R/\overline{W}$  are equally loaded ( $\pm 20\%$ ), subtract 5 ns from the values given in these columns.
7. The minimum value must be met to guarantee proper operation. If the maximum value is exceeded,  $\overline{BG}$  may be reasserted.



## NOTES:

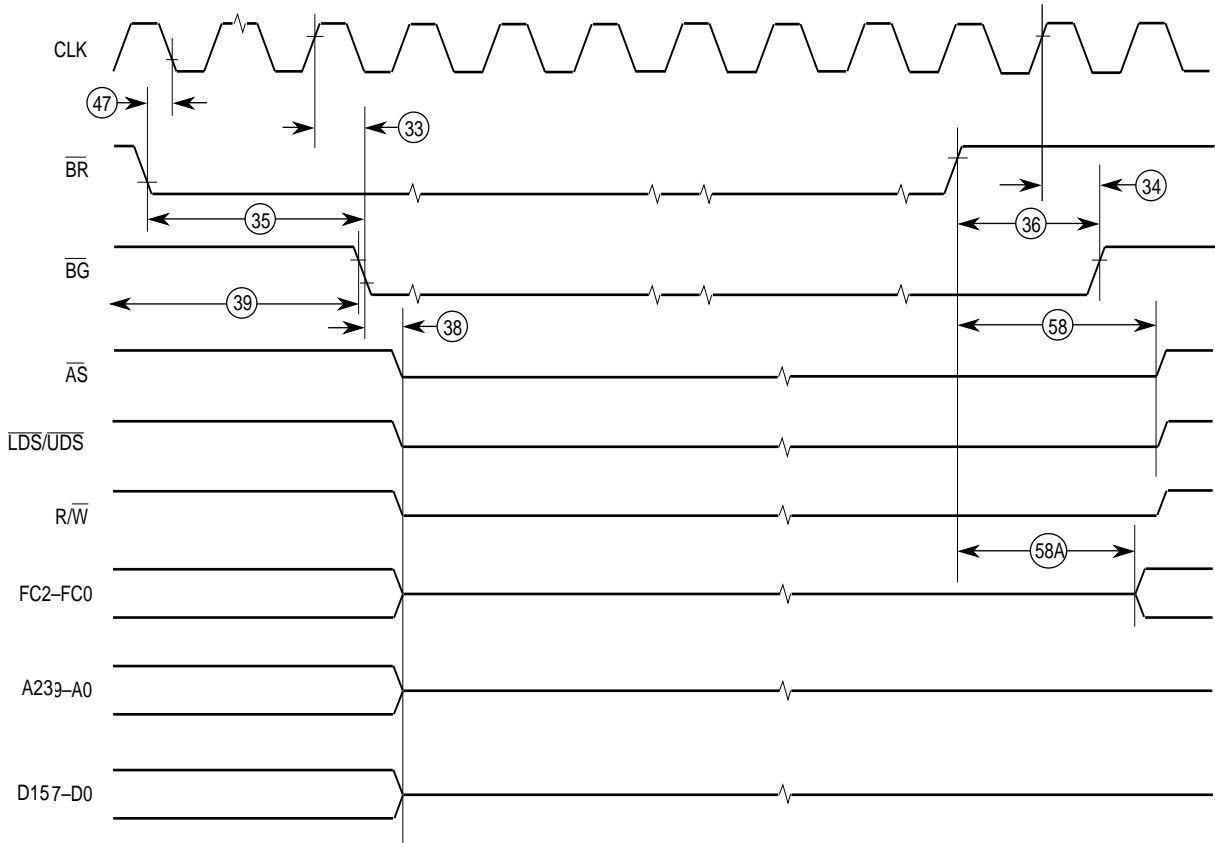
1. Setup time for the asynchronous inputs  $\overline{\text{IPL2}}\text{--}\overline{\text{IPL0}}$  and  $\overline{\text{AVEC}}$  (#47) guarantees their recognition at the next falling edge of the clock.
2. BR need fall at this time only to insure being recognized at the end of the bus cycle.
3. Timing measurements are referenced to and from a low voltage of 0.8 V and a high voltage of 2.0 V, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall is linear between 0.8 V and 2.0 V.

**Figure 9. MC68SEC000 Read Cycle Timing Diagram**



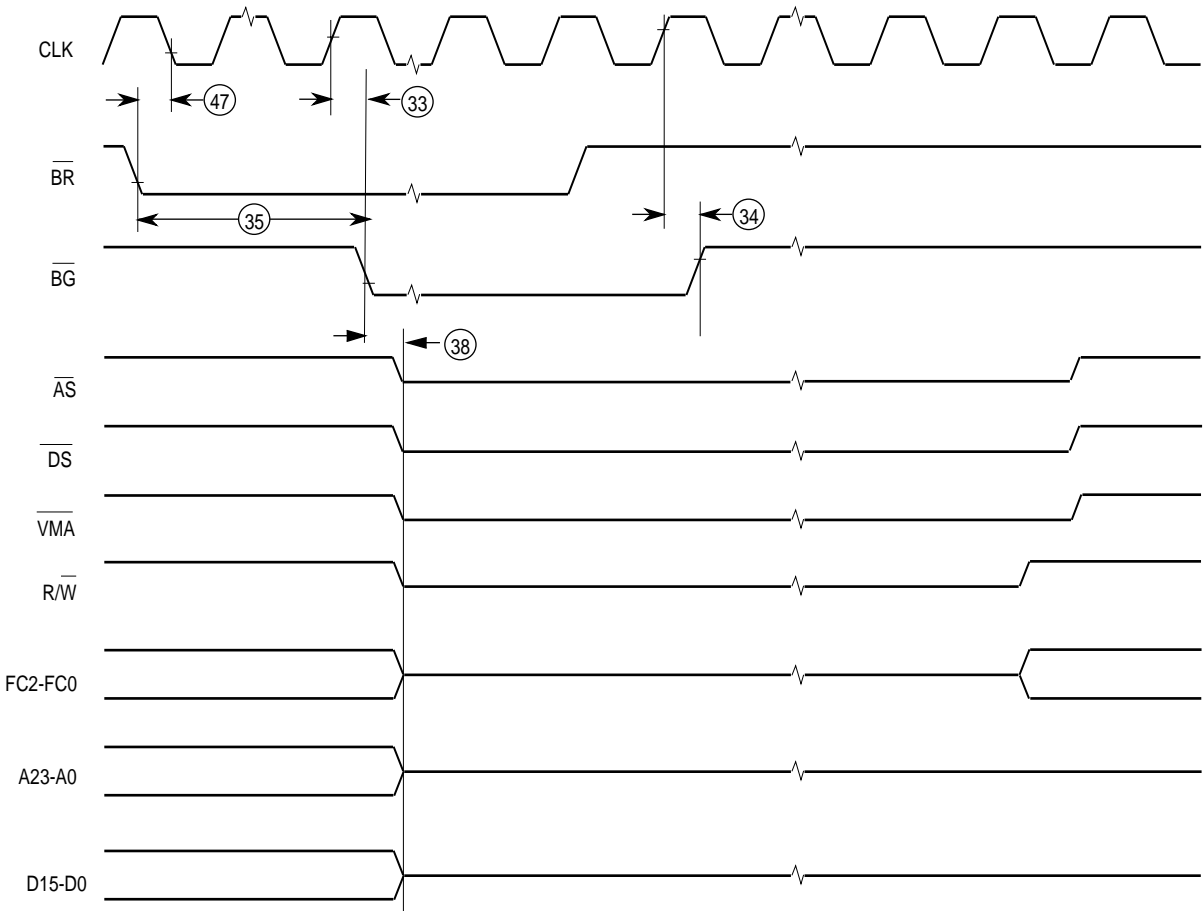
NOTE: Setup time to the clock (#47) for the asynchronous inputs BERR, BR, DTACK, IPL2-IPL0, and VPA guarantees their recognition at the next falling edge of the clock.

Figure 11. Bus Arbitration Timing



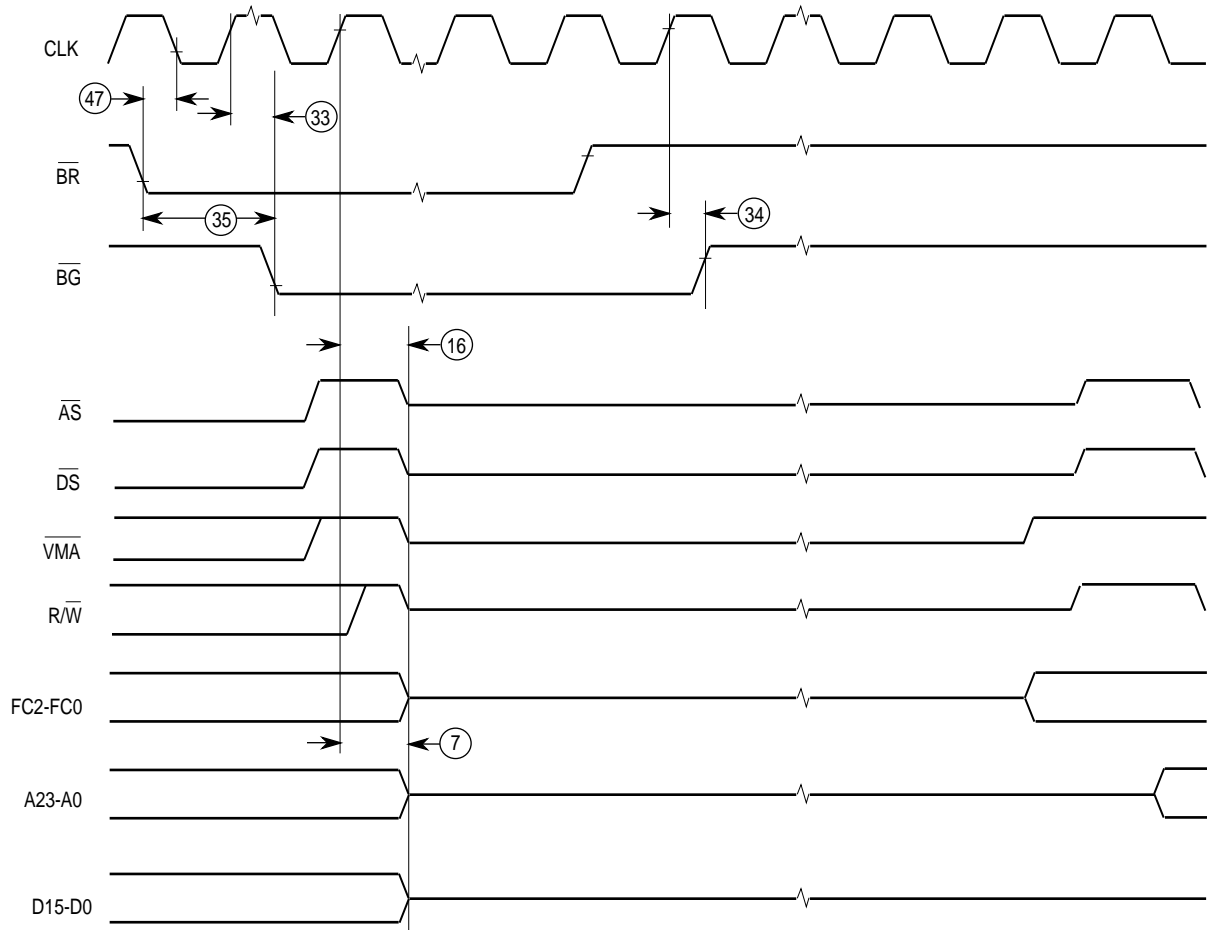
NOTE: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V.

Figure 12. MC68SEC000 Bus Arbitration Timing Diagram



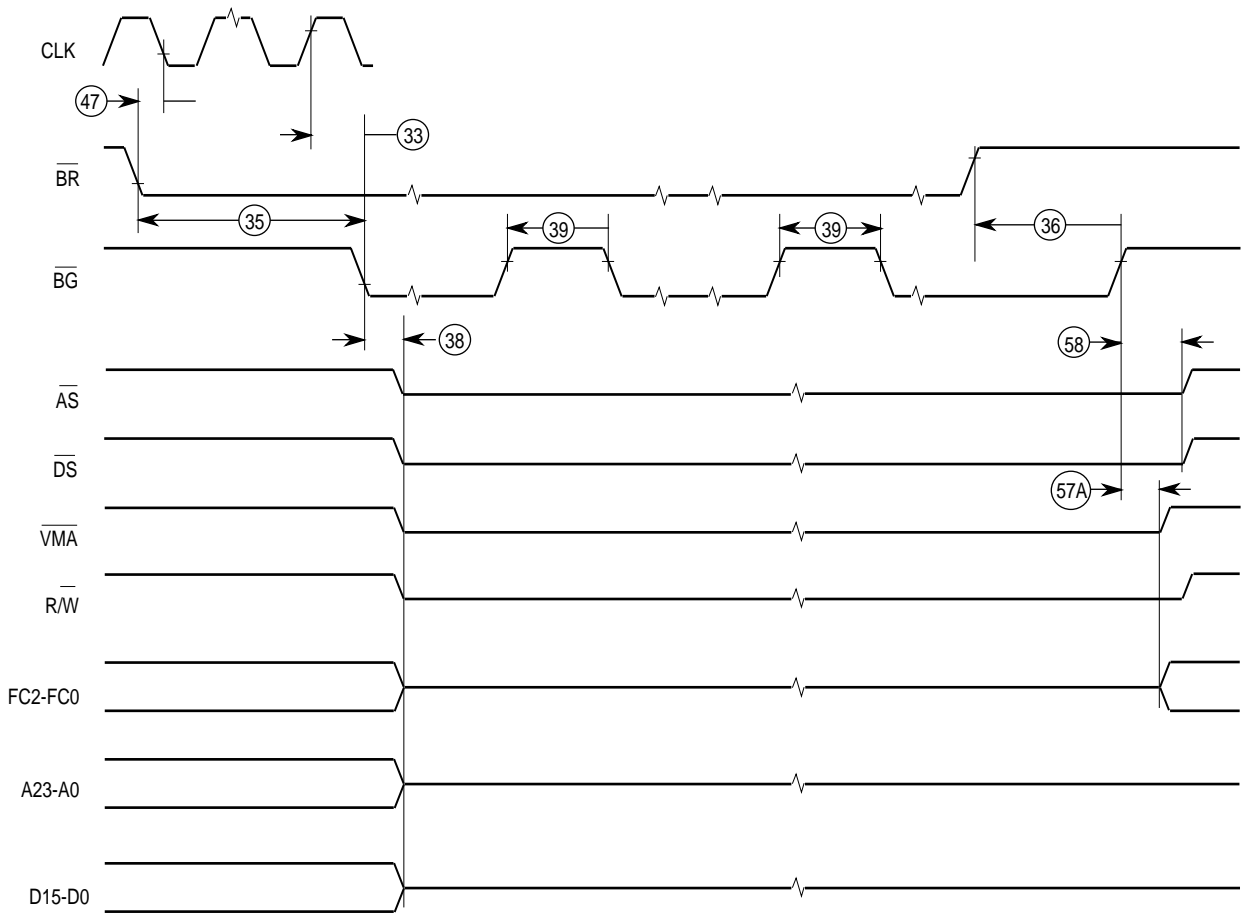
NOTES: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V. This diagram also applies to the 68EC000.

Figure 13. Bus Arbitration Timing—Idle Bus Case



NOTE: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V.  
This diagram also applies to the 68EC000.

Figure 14. Bus Arbitration Timing - Active Bus Case



NOTES: Waveform measurements for all inputs and outputs are specified at: logic high 2.0 V, logic low = 0.8 V.  
This diagram also applies to the 68EC000.

Figure 15. Bus Arbitration - Multiple Bus Request

9.0 MECHANICAL DATA

9.1 PIN ASSIGNMENTS

Add Figure 12 to Section 11.1.

The following defines the pin assignment and the package dimensions of the 64 lead QFP (FU package) and 64 lead TQFP (PB package) for the MC68SEC000. Note that it is pin-to-pin compatible with the MC68EC000.

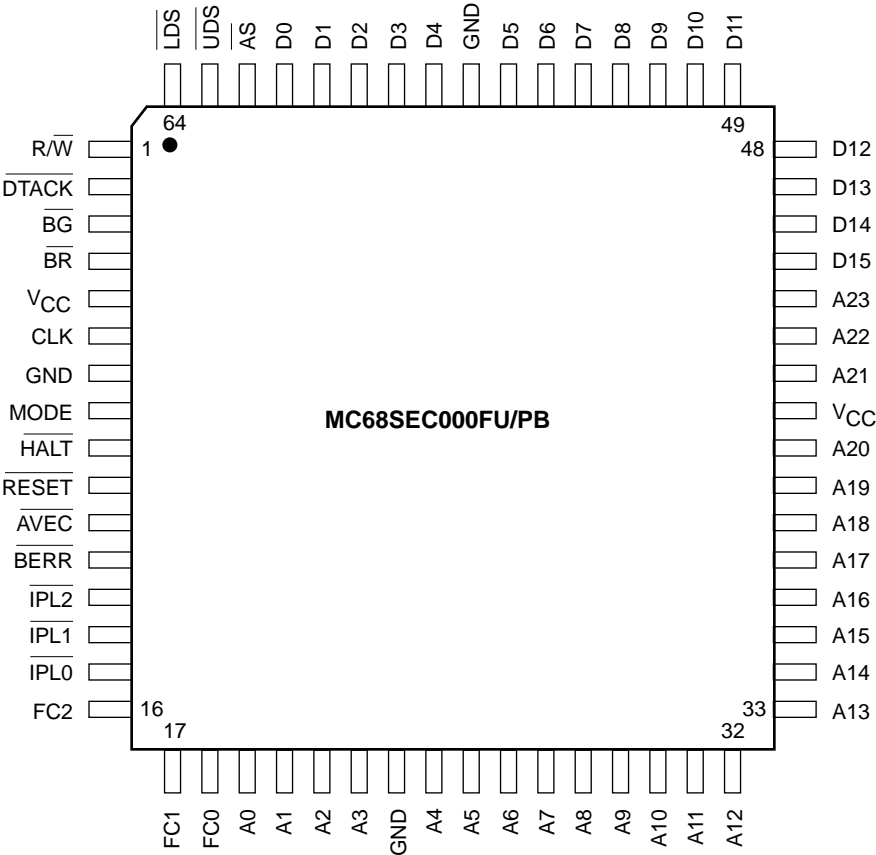


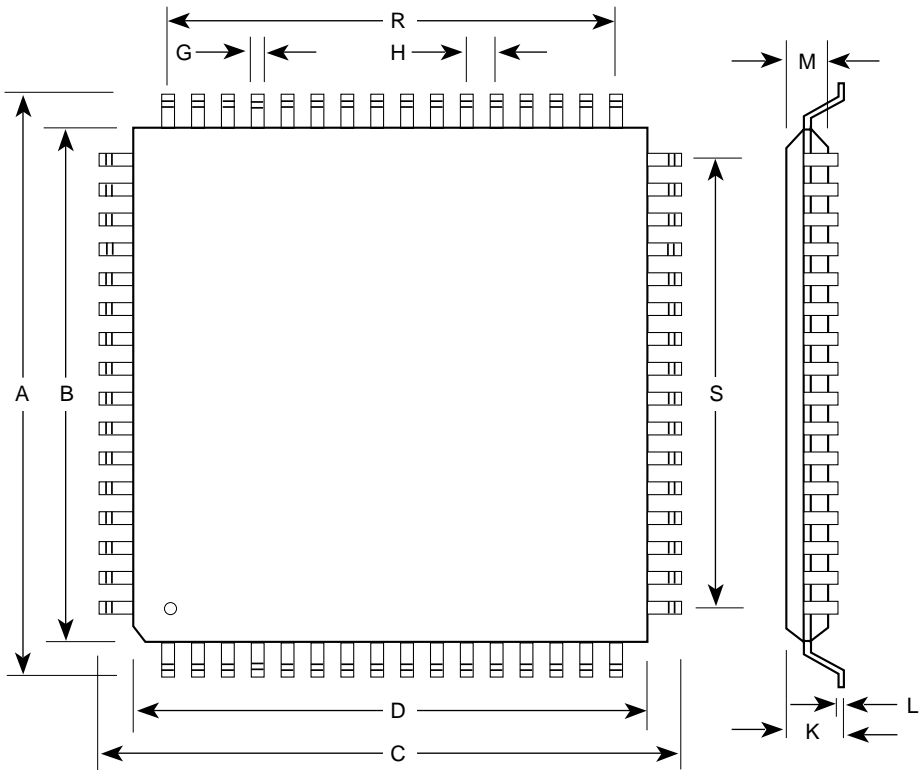
Figure 16. 64-Lead Quad Flat Pack and 64-Lead Thin Quad Flat Pack



10.0 PACKAGE DIMENSIONS - FU SUFFIX

This diagram replaces the one on Page 11-16

64 Lead Quad Flat Pack Case 840B-01

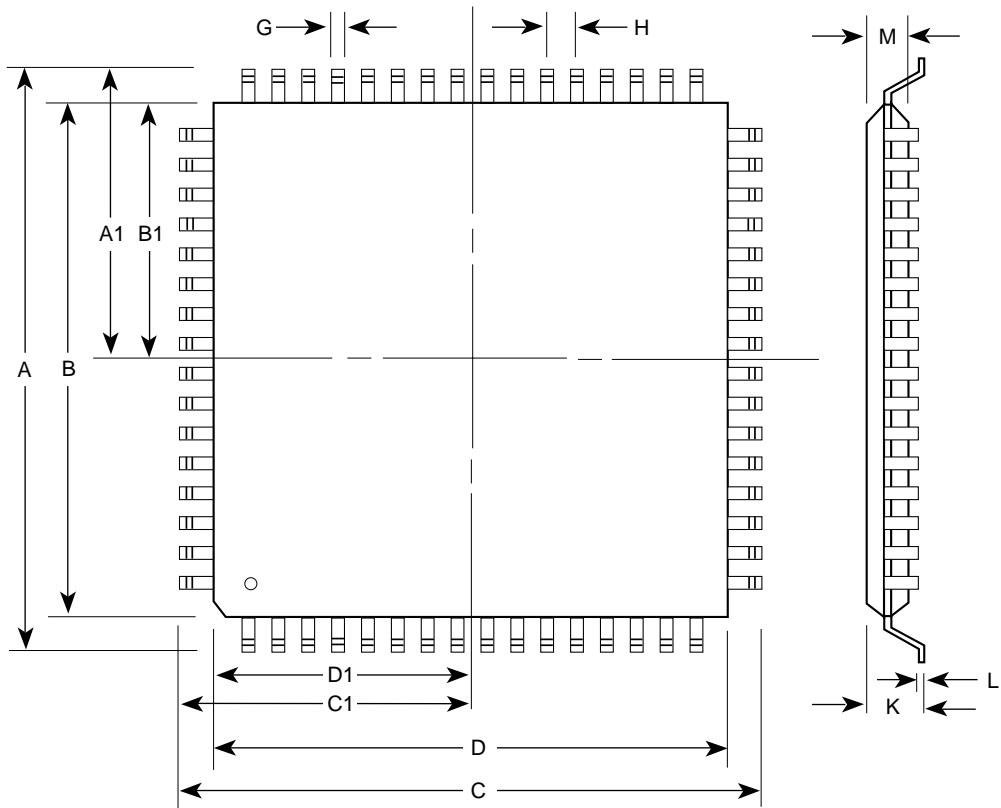


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	16.95	17.45	0.667	0.687
B	13.90	14.10	0.547	0.555
C	16.95	17.45	0.667	0.687
D	13.90	14.10	0.547	0.555
G	0.30	0.45	0.012	0.018
H	0.80 BSC		0.031 BSC	
K	2.15	2.45	0.085	0.096
L	0.13	0.23	0.005	0.009
M	2.00	2.40	0.79	0.094
R	12.00 REF		0.472 REF	
S	12.00 REF		0.472 REF	

11.0 PACKAGE DIMENSIONS - PB SUFFIX

Add the following to Section 11.2.

64 Lead Thin Quad Flat Pack Case 840F-02



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.00 BSC		0.472 BSC	
A1	6.00 BSC		0.236 BSC	
B	10.00 BSC		0.394 BSC	
B1	5.00 BSC		0.197 BSC	
C	12.00 BSC		0.472 BSC	
C1	6.00 BSC		0.236 BSC	
D	10.00 BSC		0.394 BSC	
D1	5.00 BSC		0.197 BSC	
G	0.17	0.27	0.007	0.011
H	0.50 BSC		0.020 BSC	
K	---	1.60	---	0.063
L	0.09	0.20	0.004	0.008
M	1.35	1.45	0.053	0.057

## 12.0 PACKAGE/FREQUENCY AVAILABILITY

Replaces Section 11.1

The following tables identify the packages and operating frequencies available for the MC68HC000, MC68HC001, MC68EC000, and the MC68SEC000.

MC68SEC000 PACKAGE	FREQUENCY	VOLTAGE	
		3.3 V	5 V
Quad Flat Pack (FU)	10 MHz	✓	✓
	16 MHz	✓	✓
	20MHz	✓	✓
Thin Quad Flat Pack (PB)	10 MHz	✓	✓
	16 MHz	✓	✓
	20MHz	✓	✓

MC68HC000 PACKAGE	FREQUENCY	VOLTAGE 5V
Plastic DIP	8,10,12,16,20 MHz	3
Plastic Quad Pack (PLCC)	8,10,12,16,20 MHz	3
Plastic Quad (Gull Wing)**	8,10,12,16,20 MHz	3
Pin Grid Array, Solder Lead Finish**	8,10,12,16,20 MHz	3
Pin Grid Array, Gold Lead Finish**	8,10,12,16,20 MHz	3
Plastic Quad Pack (PLCC)	8,10,12,16,20 MHz	3

MC68HC001** PACKAGE	FREQUENCY	VOLTAGE 5V
Plastic Quad Pack (PLCC)	8,10,12,16 MHz	✓
Plastic Quad (Gull Wing)	8,10,12,16 MHz	✓
Pin Grid Array, Gold Lead Finish	8,10,12,16 MHz	✓
	8,10,12,16 MHz	✓

MC68EC000 PACKAGE	FREQUENCY	VOLTAGE 5V
Plastic Quad Pack (PLCC)	8 MHz	✓
Plastic Quad Flat Pack	10 MHz	✓
	12 MHz	✓
	16 MHz	✓
	20 MHz	✓

NOTE : \*\* not recommended for new designs

## ORDERING INFORMATION

Add the following to Section 11.

The following tables contains the ordering information for the MC68SEC000.

**MC68SEC000 Ordering Information**

PACKAGE	BODY SIZE	LEAD SPACING	SPEED (IN MH Z)	VOLTAGE	SUFFIX	TEMPERATURE RANGE
QFP	14.0 mm X 14.0mm	0.8mm	10/16/20 MHz	3.3V or 5.0V	FU	0C to +70C
					CFU	-40C to +85C
TQFP	10.0mm x 10.0mm	0.5mm			PB	0C to +70C
					CPB	-40C to +85C

**MC68HC000 Ordering Information**

PACKAGE	BODY SIZE	LEAD SPACING	SPEED (IN MHZ)	VOLTAGE	SUFFIX	TEMPERATURE RANGE
DIP	81.91mm X 20.57mm	2.54mm	8, 10, 12, 16	5.0V	P	0C to +70C
PLCC	25.57mm X 25.27mm	1.27mm	8, 10, 12, 16, 20		FN	0C to +70C
			8, 10, 12, 16		CFN	-40C to +85C

**MC68EC000 Ordering Information**

PACKAGE	BODY SIZE	LEAD SPACING	SPEED (IN MHZ)	VOLTAGE	SUFFIX	TEMPERATURE RANGE
PLCC	25.57mm X 25.27mm	1.27mm	8, 10, 12, 16, 20	5.0V	FN	0C to +70C
PQFP	14.1mm X 14.1mm	0.8mm	8, 10, 12, 16, 20		FU	

## DOCUMENTATION


Add to Section 11.

The documents listed in the following table contain detailed information that pertain to the MC68SEC000 processor. You can obtain these documents from the Literature Distribution Centers listed on the last page of this document.

**MC68SEC000 Documentation**

MC68SEC000 DOCUMENTATION	DOCUMENT NUMBER
M68000 Family Programmer's Reference Manual	M68000PM/AD
M68000 User's Manual	M68000UM/AD
High Performance Embedded Systems Source Catalog	BR729/D
MC68EC000 Product Brief	MC68EC000/D
MC68SEC000 Product Brief	MC68SEC000/D



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